

IN THE CLAIMS

Claims 12-19, 30-37 and 39-41 are pending. Claims 12, 13, 18, 19, 30, 32-34, 36-37, and 39-40 are amended. Claim 38 is canceled. Claim 41 is new.

1.-11. (Canceled)

12. (Currently amended) A method comprising:

~~providing a first substrate;~~

~~predetermining a device placement location for a second substrate to be coupled to said first substrate;~~

~~predetermining a flow modifier height at least equal to a distance from a bottom surface of a second substrate used to couple said second substrate to said first substrate, to a top surface of said first substrate that is coupled to said second substrate;~~

~~coupling a pair of flow modifiers to said a first substrate substantially adjacent to said to form an adjacent border extending along only two sides of a device placement location and extending to a height substantially equal to said predetermined flow modifier height;~~

~~coupling said a second substrate to said first substrate at said device placement location, leaving a gap between the coupled surfaces having a height less than or equal to that of said pair of flow modifiers;~~

~~applying a first molding compound over said second substrate; and~~

~~applying a second molding compound between said first substrate and said second substrate, wherein said pair of flow modifiers substantially separates a flow of said first molding compound from a flow of said second molding compound.~~

13. (Currently amended) The method of claim 12 wherein said ~~flow-modifier~~ height of said flow modifiers is a distance approximately between 75 microns and 400 microns.

14. (Original) The method of claim 12 further comprising applying a low pressure over said substrates.

15. (Original) The method of claim 12 wherein said applying the first molding compound over said second substrate and applying said second molding compound between said first substrate and said second substrate happen at substantially the same time.

16. (Original) The method of claim 12 wherein applying said first molding compound over said second substrate happens before applying said second molding compound between said first substrate and said second substrate.

17. (Original) The method of claim 12 wherein applying said first molding compound over said second substrate happens after applying said second molding compound between said first substrate and said second substrate

18. (Currently amended) The method of claim 12 wherein the second substrate ~~has not been~~ is coupled to said first substrate ~~before~~ after said ~~flow-modifier~~ pair of flow modifiers are deposited.

19. (Currently amended) The method of claim 12 wherein ~~said flow-modifier~~ is each of

~~said pair of flow modifiers placed substantially around~~ further about said device placement locations an adjacent device placement location.

20-29. (Canceled)

30. (Currently amended) The method of claim 12, wherein said ~~flow modifier has predetermined~~ pair of flow modifiers have a height greater than a distance from a bottom surface of a second substrate used to couple said second substrate to said first substrate that is coupled to said second substrate the gap between the coupled surfaces.

31. (Previously presented) The method of claim 12, wherein said first molding compound has the same composition as said second molding compound.

32. (Currently amended) The method of claim 12, wherein said ~~first~~ second substrate is an integrated circuit die and said ~~second~~ first substrate is a package substrate.

33. (Currently amended) A method comprising:

~~providing a first substrate;~~

~~predetermining a device placement location for a second substrate to be coupled to said first substrate;~~

~~predetermining a flow modifier height at least equal to a distance from a bottom surface of a second substrate used to couple said second substrate to said first substrate, to a top surface of said first substrate that is coupled to said second substrate;~~

coupling a pair of flow modifiers to said ~~a~~ first substrate ~~substantially adjacent to said~~
~~to form an adjacent border extending along only two sides of a device placement location and~~
~~extending to a height substantially equal to said predetermined flow modifier height;~~

coupling said ~~a~~ second substrate to said first substrate at said device placement
location, leaving a gap between the coupled surfaces having a height less than or equal to that
of said pair of flow modifiers;

introducing a first molding compound over said second substrate and a second
molding compound between said first substrate and said second substrate ~~at substantially the~~
~~same time. and;~~

bifurcating each of said pair of flow modifiers to singulate said device placement
location from an adjacent device placement location.

34. (Currently amended) The method of claim 33 wherein ~~said flow modifier has~~
~~predetermined~~ said pair of flow modifiers have a height greater than a distance from a bottom
~~surface of a second substrate used to couple said second substrate to said first substrate that is~~
~~coupled to said second substrate~~ the gap between the coupled surfaces.

35. (Previously presented) The method of claim 33 wherein said first molding compound
has the same composition as said second molding compound.

36. (Currently amended) A method comprising:

providing a substrate having a first and second die placement location;

forming a ~~flow modifier substantially adjacent to a~~ on the substrate a pair of flow
modifiers bordering two opposite sides of said first and second die placement location;

coupling ~~a surface of a~~ first die to ~~a surface of~~ said substrate at said first die placement location and coupling a second die to said substrate at said second die placement location, wherein said coupling forms a gap between the coupled surfaces having a height less than or equal to that of said first and second flow modifier;

introducing molding compound to a side of said first die to overmolding overmold said first and second die ~~with a first mold flow~~; and

introducing molding compound to a side of said first die to underfilling underfill said gap between said die and said substrate ~~with a second mold flow~~ coupled surfaces of said first and second die to said substate, wherein said ~~second mold flow is substantially separated from said first mold flow by said flow modifier~~ pair of flow modifiers substantially separates an overmold flow from an underfill flow.

37. (Currently amended) The method of claim 36, wherein said ~~first mold flow and said second mold flow~~ overmold and said underfill are initiated at substantially the same time.

38. (Canceled)

39. (Currently amended) The method of claim 36, wherein said ~~overmolding overmold~~ is performed before said underfilling underfill.

40. (Currently amended) The method of claim 36, wherein said ~~overmolding overmold~~ is performed with the same molding compound as said underfilling underfill.

41. (New) The method of claim 36, further comprising singulating said first and second die from adjacent die placement locations by bifurcating each of said pair of flow modifiers.